Renesas Electronics America Inc - R5F2134CWKFP#U0 Datasheet

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Not For New Designs
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	CANbus, I²C, IEBus, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	43
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2134cwkfp-u0

1.3 Block Diagram

Figure 1.5 shows a Block Diagram.

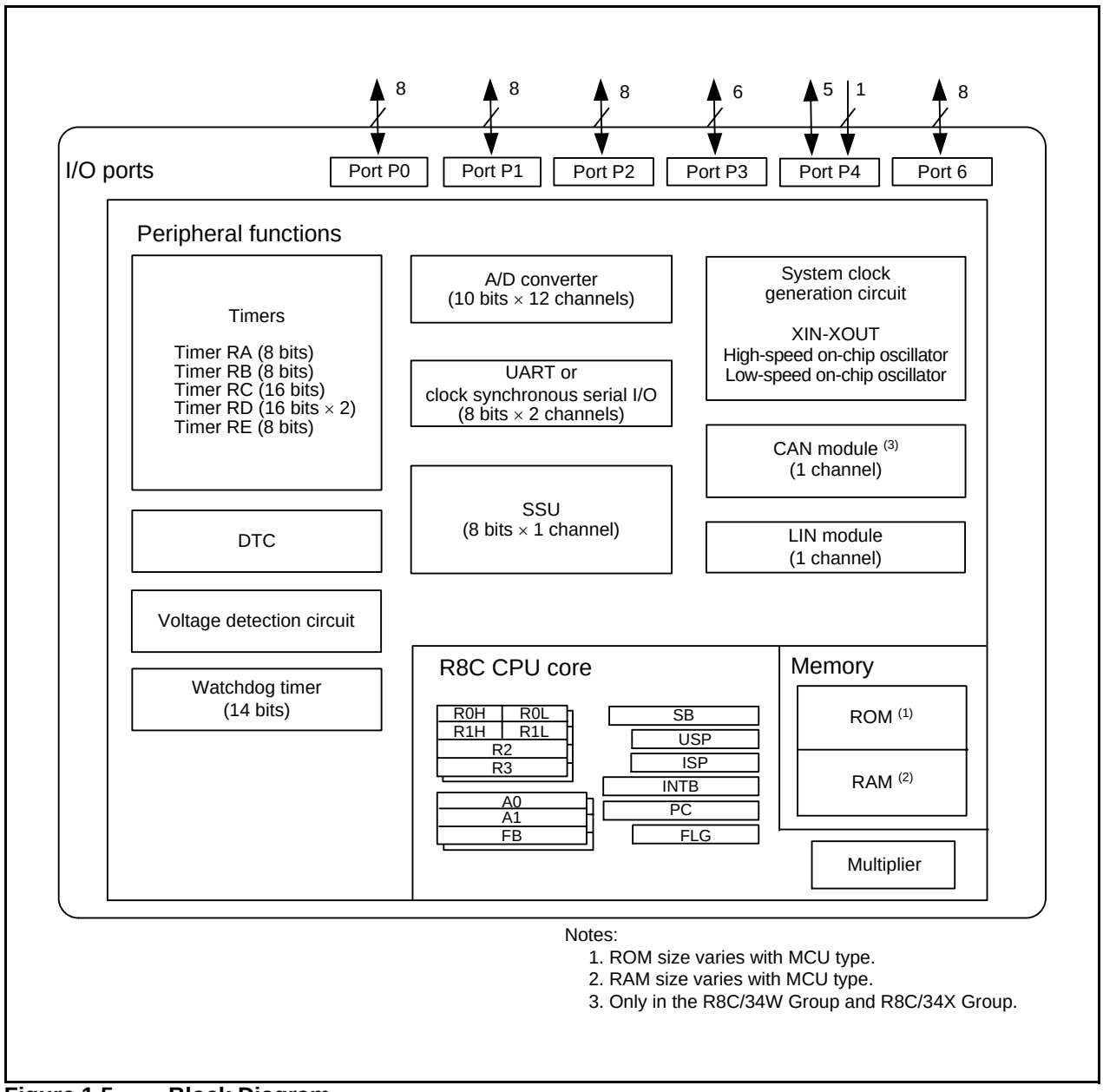


Figure 1.5 Block Diagram

1.5 Pin Functions

Tables 1.15 and 1.16 list Pin Functions.

Table 1.15 Pin Functions (1)

Item	Pin Name	I/O Type	Description
Power supply input	VCC, VSS	–	Apply 2.7 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	–	Power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset input	$\overline{\text{RESET}}$	I	Input “L” on this pin resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
XIN clock input	XIN	I	These pins are provided for XIN clock generation circuit I/O. Connect a ceramic resonator or a crystal oscillator between the XIN and XOUT pins (1). To use an external clock, input it to the XOUT pin and leave the XIN pin open.
XIN clock output	XOUT	I/O	
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT0}}$ to $\overline{\text{INT4}}$	I	$\overline{\text{INT}}$ interrupt input pins.
Key input interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	Key input interrupt input pins
Timer RA	TRAIO	I/O	Timer RA I/O pin
	TRAO	O	Timer RA output pin
Timer RB	TRBO	O	Timer RB output pin
Timer RC	TRCCLK	I	External clock input pin
	TRCTRG	I	External trigger input pin
	TRCIOA, TRCIOB, TRCIOC, TRCIOD	I/O	Timer RC I/O pins
Timer RD	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDIOC0, TRDIOC1, TRDIOD0, TRDIOD1	I/O	Timer RD I/O pins
	TRDCLK	I	External clock input pin
Timer RE	TREO	O	Divided clock output pin
Serial interface	CLK0, CLK2	I/O	Transfer clock I/O pins
	RXD0, RXD2	I	Serial data input pins
	TXD0, TXD2	O	Serial data output pins
	$\overline{\text{CTS2}}$	I	Transmission control input pin
	$\overline{\text{RTS2}}$	O	Reception control output pin
	SCL2	I/O	I^2C mode clock I/O pin
	SDA2	I/O	I^2C mode data I/O pin
SSU	SSI	I/O	Data I/O pin
	$\overline{\text{SCS}}$	I/O	Chip-select signal I/O pin
	SSCK	I/O	Clock I/O pin
	SSO	I/O	Data I/O pin

I: Input O: Output I/O: Input and output

Note:

1. Refer to the oscillator manufacturer for oscillation characteristics.

2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3. R0 can be split into high-order bits (R0H) and low-order bits (R0L) to be used separately as 8-bit data registers. R1H and R1L are analogous to R0H and R0L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 is analogous to A0. A1 can be combined with A0 and as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the start address of an interrupt vector table.

2.5 Program Counter (PC)

PC is 20 bits wide and indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP, and ISP, are each 16 bits wide. The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated by the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0; otherwise to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value; otherwise to 0.

2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is set to 1.

2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow; otherwise to 0.

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.
Interrupt are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.
The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns processor interrupt priority levels from level 0 to level 7.
If a requested interrupt has higher priority than IPL, the interrupt is enabled.

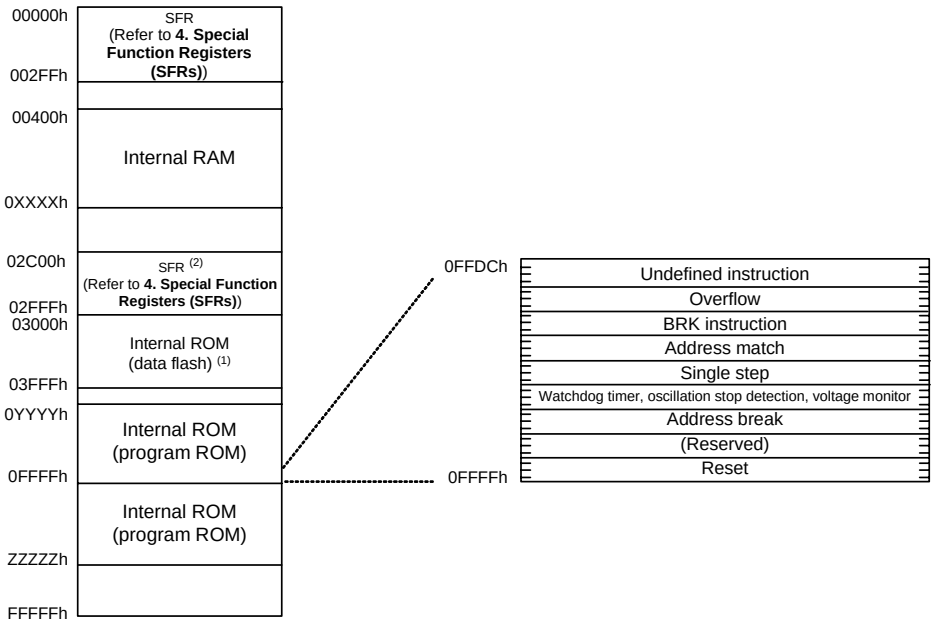
2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.

3. Memory

3.1 R8C/34W Group

Figure 3.1 is a Memory Map of R8C/34W Group. The R8C/34W Group has a 1-Mbyte address space from addresses 00000h to FFFFFh. The internal ROM (program ROM) is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.
The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. The starting address of each interrupt routine is stored here.
The internal ROM (data flash) is allocated addresses 03000h to 03FFFh.
The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 4-Kbyte internal RAM area is allocated addresses 00400h to 013FFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.
Special function registers (SFRs) are allocated addresses 00000h to 002FFh and 02C00h to 02FFFh (the SFR areas for the CAN, DTC, and other modules). Peripheral function control registers are allocated here. All unallocated spaces within the SFRs are reserved and cannot be accessed by users.



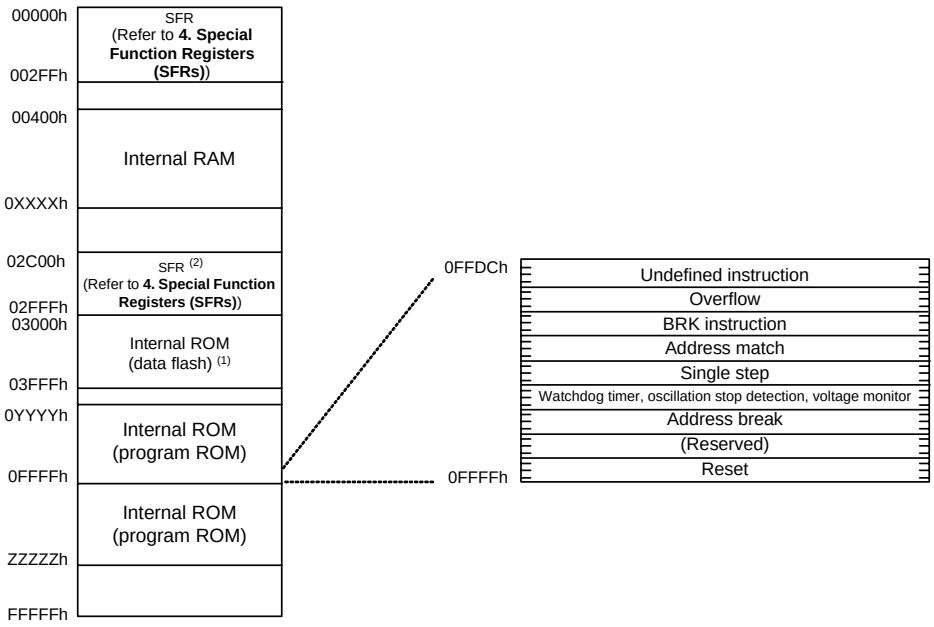
Notes:
1. The Data Flash memory indicates blocks A (1 Kbyte), B (1 Kbyte), C (1 Kbyte), and D (1 Kbyte).
2. The SFR areas for the CAN, DTC and other modules are allocated to addresses 02C00h to 02FFFh.
3. The blank areas are reserved and cannot be accessed by users.

Part Number	Internal ROM			Internal RAM	
	Size	Address 0YYYYh	Address ZZZZZh	Size	Address 0XXXXh
R5F21346WJFP, R5F21346WKFP	32 Kbytes	08000h	—	2.5 Kbytes	00DFFh
R5F21347WJFP, R5F21347WKFP	48 Kbytes	04000h	—	4 Kbytes	013FFh
R5F21348WJFP, R5F21348WKFP	64 Kbytes	04000h	13FFFh	6 Kbytes	01BFFh
R5F2134AWJFP, R5F2134AWKFP	96 Kbytes	04000h	1BFFFh	8 Kbytes	023FFh
R5F2134CWJFP, R5F2134CWKFP	128 Kbytes	04000h	23FFFh	10 Kbytes	02BFFh

Figure 3.1 Memory Map of R8C/34W Group

3.3 R8C/34Y Group

Figure 3.3 is a Memory Map of R8C/34Y Group. The R8C/34Y Group has a 1-Mbyte address space from addresses 00000h to FFFFFh. The internal ROM (program ROM) is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.
The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. The starting address of each interrupt routine is stored here.
The internal ROM (data flash) is allocated addresses 03000h to 03FFFh.
The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 4-Kbyte internal RAM area is allocated addresses 00400h to 013FFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.
Special function registers (SFRs) are allocated addresses 00000h to 002FFh and 02C00h to 02FFFh (the SFR areas for the DTC and other modules). Peripheral function control registers are allocated here. All unallocated spaces within the SFRs are reserved and cannot be accessed by users.



Notes:
1. The Data Flash memory indicates blocks A (1 Kbyte), B (1 Kbyte), C (1 Kbyte), and D (1 Kbyte).
2. The SFR areas for the DTC and other modules are allocated to addresses 02C00h to 02FFFh.
3. The blank areas are reserved and cannot be accessed by users.

Part Number	Internal ROM			Internal RAM	
	Size	Address 0YYYYh	Address ZZZZZh	Size	Address 0XXXXh
R5F21346YJFP, R5F21346YKFP	32 Kbytes	08000h	—	2.5 Kbytes	00DFFh
R5F21347YJFP, R5F21347YKFP	48 Kbytes	04000h	—	4 Kbytes	013FFh
R5F21348YJFP, R5F21348YKFP	64 Kbytes	04000h	13FFFh	6 Kbytes	01BFFh
R5F2134AYJFP, R5F2134AYKFP	96 Kbytes	04000h	1BFFFh	8 Kbytes	023FFh
R5F2134CYJFP, R5F2134CYKFP	128 Kbytes	04000h	23FFFh	10 Kbytes	02BFFh

Figure 3.3 Memory Map of R8C/34Y Group

Table 4.2 SFR Information (2) (1)

Address	Register	Symbol	After reset
003Ah	Voltage Monitor 2 Circuit Control Register	VW2C	10000010b
003Bh			
003Ch			
003Dh			
003Eh			
003Fh			
0040h			
0041h	Flash Memory Ready Interrupt Control Register	FMRDYIC	XXXXX000b
0042h			
0043h			
0044h			
0045h			
0046h	INT4 Interrupt Control Register	INT4IC	XX00X000b
0047h	Timer RC Interrupt Control Register	TRCIC	XXXXX000b
0048h	Timer RD0 Interrupt Control Register	TRD0IC	XXXXX000b
0049h	Timer RD1 Interrupt Control Register	TRD1IC	XXXXX000b
004Ah	Timer RE Interrupt Control Register	TREIC	XXXXX000b
004Bh	UART2 Transmit Interrupt Control Register	S2TIC	XXXXX000b
004Ch	UART2 Receive Interrupt Control Register	S2RIC	XXXXX000b
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh	SSU Interrupt Control Register	SSUIC	XXXXX000b
0050h			
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h			
0054h			
0055h	INT2 Interrupt Control Register	INT2IC	XX00X000b
0056h	Timer RA Interrupt Control Register	TRAIC	XXXXX000b
0057h			
0058h	Timer RB Interrupt Control Register	TRBIC	XXXXX000b
0059h	INT1 Interrupt Control Register	INT1IC	XX00X000b
005Ah	INT3 Interrupt Control Register	INT3IC	XX00X000b
005Bh			
005Ch			
005Dh	INT0 Interrupt Control Register	INT0IC	XX00X000b
005Eh	UART2 Bus Collision Detection Interrupt Control Register	U2BCNIC	XXXXX000b
005Fh			
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h			
006Ah			
006Bh			
006Ch	CAN0 Reception Complete Interrupt Control Register	C0RIC	XXXXX000b
006Dh	CAN0 Transmission Complete Interrupt Control Register	C0TIC	XXXXX000b
006Eh	CAN0 Receive FIFO Interrupt Control Register	C0FRIC	XXXXX000b
006Fh	CAN0 Transmit FIFO Interrupt Control Register	C0FTIC	XXXXX000b
0070h	CAN0 Error Interrupt Control Register	C0EIC	XXXXX000b
0071h	CAN0 Wake-up Interrupt Control Register	C0WIC	XXXXX000b
0072h	Voltage Monitor 1 Interrupt Control Register	VCMP1IC	XXXXX000b
0073h	Voltage Monitor 2 Interrupt Control Register	VCMP2IC	XXXXX000b
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
007Eh			
007Fh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.8 SFR Information (8) (1)

Address	Register	Symbol	After reset
01C0h	Address Match Interrupt Register 0	RMAD0	XXh
01C1h			XXh
01C2h			0000XXXXb
01C3h	Address Match Interrupt Enable Register 0	AIER0	00h
01C4h	Address Match Interrupt Register 1	RMAD1	XXh
01C5h			XXh
01C6h			0000XXXXb
01C7h	Address Match Interrupt Enable Register 1	AIER1	00h
01C8h			
01C9h			
01CAh			
01CBh			
01CCh			
01CDh			
01CEh			
01CFh			
01D0h			
01D1h			
01D2h			
01D3h			
01D4h			
01D5h			
01D6h			
01D7h			
01D8h			
01D9h			
01DAh			
01DBh			
01DCh			
01DDh			
01DEh			
01DFh			
01E0h	Pull-Up Control Register 0	PUR0	00h
01E1h	Pull-Up Control Register 1	PUR1	00h
01E2h			
01E3h			
01E4h			
01E5h			
01E6h			
01E7h			
01E8h			
01E9h			
01EAh			
01EBh			
01ECh			
01EDh			
01EEh			
01EFh			
01F0h			
01F1h			
01F2h			
01F3h			
01F4h			
01F5h	Input Threshold Control Register 0	VLT0	00h
01F6h	Input Threshold Control Register 1	VLT1	00h
01F7h			
01F8h			
01F9h			
01FAh	External Input Enable Register 0	INTEN	00h
01FBh	External Input Enable Register 1	INTEN1	00h
01FCh	INT Input Filter Select Register 0	INTF	00h
01FDh	INT Input Filter Select Register 1	INTF1	00h
01FEh	Key Input Enable Register 0	KIEN	00h
01FFh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.12 SFR Information (12) (1)

Address	Register	Symbol	After reset
2CF0h	DTC Control Data 22	DTCD22	XXh
2CF1h			XXh
2CF2h			XXh
2CF3h			XXh
2CF4h			XXh
2CF5h			XXh
2CF6h			XXh
2CF7h			XXh
2CF8h	DTC Control Data 23	DTCD23	XXh
2CF9h			XXh
2CFAh			XXh
2CFBh			XXh
2CFCh			XXh
2CFDh			XXh
2CFEh			XXh
2CFFh			XXh
2D00h			
2D01h			
:			
2E00h	CAN0 Mailbox 0 : Message ID	C0MB0	XXh
2E01h			XXh
2E02h			XXh
2E03h			XXh
2E04h			
2E05h	CAN0 Mailbox 0 : Data length		XXh
2E06h	CAN0 Mailbox 0 : Data field		XXh
2E07h			XXh
2E08h			XXh
2E09h			XXh
2E0Ah			XXh
2E0Bh			XXh
2E0Ch			XXh
2E0Dh			XXh
2E0Eh	CAN0 Mailbox 0 : Time stamp		XXh
2E0Fh			XXh
2E10h	CAN0 Mailbox 1 : Message ID	C0MB1	XXh
2E11h			XXh
2E12h			XXh
2E13h			XXh
2E14h			
2E15h	CAN0 Mailbox 1 : Data length		XXh
2E16h	CAN0 Mailbox 1 : Data field		XXh
2E17h			XXh
2E18h			XXh
2E19h			XXh
2E1Ah			XXh
2E1Bh			XXh
2E1Ch			XXh
2E1Dh			XXh
2E1Eh	CAN0 Mailbox 1 : Time stamp		XXh
2E1Fh			XXh
2E20h	CAN0 Mailbox 2 : Message ID	C0MB2	XXh
2E21h			XXh
2E22h			XXh
2E23h			XXh
2E24h			
2E25h	CAN0 Mailbox 2 : Data length		XXh
2E26h	CAN0 Mailbox 2 : Data field		XXh
2E27h			XXh
2E28h			XXh
2E29h			XXh
2E2Ah			XXh
2E2Bh			XXh
2E2Ch			XXh
2E2Dh			XXh
2E2Eh	CAN0 Mailbox 2 : Time stamp		XXh
2E2Fh			XXh

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.13 SFR Information (13) (1)

Address	Register	Symbol	After reset
2E30h	CAN0 Mailbox 3 : Message ID	C0MB3	XXh
2E31h			XXh
2E32h			XXh
2E33h			XXh
2E34h			
2E35h	CAN0 Mailbox 3 : Data length		XXh
2E36h	CAN0 Mailbox 3 : Data field		XXh
2E37h			XXh
2E38h			XXh
2E39h			XXh
2E3Ah			XXh
2E3Bh			XXh
2E3Ch			XXh
2E3Dh			XXh
2E3Eh	CAN0 Mailbox3 : Time stamp		XXh
2E3Fh			XXh
2E40h	CAN0 Mailbox4 : Message ID	C0MB4	XXh
2E41h			XXh
2E42h			XXh
2E43h			XXh
2E44h			
2E45h	CAN0 Mailbox4 : Data length		XXh
2E46h	CAN0 Mailbox4 : Data field		XXh
2E47h			XXh
2E48h			XXh
2E49h			XXh
2E4Ah			XXh
2E4Bh			XXh
2E4Ch			XXh
2E4Dh			XXh
2E4Eh	CAN0 Mailbox4 : Time stamp		XXh
2E4Fh			XXh
2E50h	CAN0 Mailbox5 : Message ID	C0MB5	XXh
2E51h			XXh
2E52h			XXh
2E53h			XXh
2E54h			
2E55h	CAN0 Mailbox5 : Data length		XXh
2E56h	CAN0 Mailbox5 : Data field		XXh
2E57h			XXh
2E58h			XXh
2E59h			XXh
2E5Ah			XXh
2E5Bh			XXh
2E5Ch			XXh
2E5Dh			XXh
2E5Eh	CAN0 Mailbox5 : Time stamp		XXh
2E5Fh			XXh
2E60h	CAN0 Mailbox6 : Message ID	C0MB6	XXh
2E61h			XXh
2E62h			XXh
2E63h			XXh
2E64h			
2E65h	CAN0 Mailbox6 : Data length		XXh
2E66h	CAN0 Mailbox6 : Data field		XXh
2E67h			XXh
2E68h			XXh
2E69h			XXh
2E6Ah			XXh
2E6Bh			XXh
2E6Ch			XXh
2E6Dh			XXh
2E6Eh	CAN0 Mailbox6 : Time stamp		XXh
2E6Fh			XXh

X: Undefined
Note:
1. The blank areas are reserved and cannot be accessed by users.

Table 4.17 SFR Information (17) (1)

Address	Register	Symbol	After reset
2F3Bh	CAN0 Message Control Register 11	C0MCTL11	00h
2F3Ch	CAN0 Message Control Register 12	C0MCTL12	00h
2F3Dh	CAN0 Message Control Register 13	C0MCTL13	00h
2F3Eh	CAN0 Message Control Register 14	C0MCTL14	00h
2F3Fh	CAN0 Message Control Register 15	C0MCTL15	00h
2F40h	CAN0 Control Register	C0CTLR	00000101b
2F41h			00h
2F42h	CAN0 Status Register	C0STR	00000101b
2F43h			00h
2F44h	CAN0 Bit Configuration Register	C0BCR	00h
2F45h			00h
2F46h			00h
2F47h			
2F48h	CAN0 Receive FIFO Control Register	C0RFCR	10000000b
2F49h	CAN0 Receive FIFO Pointer Control Register	C0RFPCR	XXh
2F4Ah	CAN0 Transmit FIFO Control Register	C0TFCR	10000000b
2F4Bh	CAN0 Transmit FIFO Pointer Control Register	C0TFPCR	XXh
2F4Ch	CAN0 Error Interrupt Enable Register	C0EIER	00h
2F4Dh	CAN0 Error Interrupt Factor Judge Register	C0EIFR	00h
2F4Eh	CAN0 Reception Error Count Register	C0RECR	00h
2F4Fh	CAN0 Transmission Error Count Register	C0TECR	00h
2F50h	CAN0 Error Code Store Register	C0ECSR	00h
2F51h	CAN0 Channel Search Support Register	C0CSSR	XXh
2F52h	CAN0 Mailbox Search Status Register	C0MSSR	10000000b
2F53h	CAN0 Mailbox Search Mode Register	C0MSMR	00h
2F54h	CAN0 Time Stamp Register	C0TSR	00h
2F55h			00h
2F56h	CAN0 Acceptance Filter Support Register	C0AFSR	XXh
2F57h			XXh
2F58h	CAN0 Test Control Register	C0TCR	00h
:			
2FFFh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.18 ID Code Areas and Option Function Select Area

Address	Area Name	Symbol	After Reset
:			
FFDBh	Option Function Select Register 2	OFS2	(Note 1)
:			
FFDFh	ID1		(Note 2)
:			
FFE3h	ID2		(Note 2)
:			
FFEBh	ID3		(Note 2)
:			
FFEFh	ID4		(Note 2)
:			
FFF3h	ID5		(Note 2)
:			
FFF7h	ID6		(Note 2)
:			
FFFBh	ID7		(Note 2)
:			
FFFFh	Option Function Select Register	OFS	(Note 1)

Notes:

1. The option function select area is allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program.
   Do not write additions to the option function select area. If the block including the option function select area is erased, the option function select area is set to FFh.
   When blank products are shipped, the option function select area is set to FFh. It is set to the written value after written by the user.
   When factory-programming products are shipped, the value of the option function select area is the value programmed by the user.
2. The ID code areas are allocated in the flash memory, not in the SFRs. Set appropriate values as ROM data by a program.
   Do not write additions to the ID code areas. If the block including the ID code areas is erased, the ID code areas are set to FFh.
   When blank products are shipped, the ID code areas are set to FFh. They are set to the written value after written by the user.
   When factory-programming products are shipped, the value of the ID code areas is the value programmed by the user.

5. Electrical Characteristics

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated Value	Unit
V_{CC}/AV_{CC}	Supply voltage		–0.3 to 6.5	V
V_I	Input voltage (1)		–0.3 to V_{CC} + 0.3	V
IIN	Input current (1)	(2, 3, 4)	–4 to 4	mA
V_O	Output voltage		–0.3 to V_{CC} + 0.3	V
P_d	Power dissipation	–40 °C ≤ T_{opr} < 85 °C	300	mW
		85 °C ≤ T_{opr} < 125 °C	125	mW
T_{opr}	Operating ambient temperature		–40 to 85 (J version) / –40 to 125 (K version)	°C
T_{stg}	Storage temperature		–65 to 150	°C

Notes:
1. Meet the specified range for the input voltage or the input current.
2. Applicable ports: P0 to P2, P3_0, P3_1, P3_3 to P3_5, P3_7, P4_3 to P4_5, P6
3. The total input current must be 12 mA or less.
4. Even if no voltage is supplied to Vcc, the input current may cause the MCU to be powered on and operate. When a voltage is supplied to Vcc, the input current may cause the supply voltage to rise. Since operations in any cases other than above are not guaranteed, use the power supply circuit in the system to ensure the supply voltage for the MCU is stable within the specified range.

Table 5.4 A/D Converter Characteristics

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
–	Resolution		V_{ref} = AV_{CC}		–	–	10	Bit
–	Absolute accuracy	10-bit mode	V_{ref} = AV_{CC} = 5.0 V	AN0 to AN7 input, AN8 to AN11 input	–	–	±3	LSB
			V_{ref} = AV_{CC} = 3.0 V	AN0 to AN7 input, AN8 to AN11 input	–	–	±5	LSB
		8-bit mode	V_{ref} = AV_{CC} = 5.0 V	AN0 to AN7 input, AN8 to AN11 input	–	–	±2	LSB
			V_{ref} = AV_{CC} = 3.0 V	AN0 to AN7 input, AN8 to AN11 input	–	–	±2	LSB
ϕAD	A/D conversion clock		4.0 ≤ V_{ref} = AV_{CC} = ≤ 5.5 (2)		2	–	20	MHz
			2.7 ≤ V_{ref} = AV_{CC} = ≤ 5.5 (2)		2	–	10	MHz
–	Tolerance level impedance				–	3	–	kΩ
I_{vref}	V_{ref} current		V_{CC} = 5.0 V, XIN = f1 = ϕAD = 20 MHz		–	45	–	µA
t_{CONV}	Conversion time	10-bit mode	V_{ref} = AV_{CC} = 5.0 V, ϕAD = 20 MHz		2.2	–	–	µs
		8-bit mode	V_{ref} = AV_{CC} = 5.0 V, ϕAD = 20 MHz		2.2	–	–	µs
t_{SAMP}	Sampling time		ϕAD = 20 MHz		0.8	–	–	µs
V_{ref}	Reference voltage				2.7	–	AV_{CC}	V
V_{IA}	Analog input voltage (3)				0	–	V_{ref}	V
OCVREF	On-chip reference voltage		2 MHz ≤ ϕAD ≤ 4 MHz		1.14	1.34	1.54	V

Notes:
1. V_{CC}/AV_{CC} = V_{ref} = 2.7 to 5.5 V, V_{SS} = 0 V at T_{opr} = –40 to 85°C (J version) / –40 to 125°C (K version), unless otherwise specified.
2. The A/D conversion result will be undefined in wait mode, stop mode, when the flash memory stops, and in low-consumption current mode. Do not perform A/D conversion in these states or transition to these states during A/D conversion.
3. When the analog input voltage is over the reference voltage, the A/D conversion result will be 3FFh in 10-bit mode and FFh in 8-bit mode.

Table 5.6 Flash Memory (Data flash Block A to Block D) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/erase endurance (2)		10,000 (3)	–	–	times
–	Byte program time (program/erase endurance ≤ 1,000 times)		–	160	950	µs
–	Byte program time (program/erase endurance > 1,000 times)		–	300	950	µs
–	Block erase time (program/erase endurance ≤ 1,000 times)		–	0.2	1	s
–	Block erase time (program/erase endurance > 1,000 times)		–	0.3	1	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend		–	–	3+CPU clock × 3 cycles	ms
–	Interval from erase start/restart until following suspend request		0	–	–	µs
–	Time from suspend until erase restart		–	–	30+CPU clock × 1 cycle	µs
$t_{d(CMDRST-READY)}$	Time from when command is forcibly terminated until reading is enabled		–	–	30+CPU clock × 1 cycle	µs
–	Program, erase voltage		2.7	–	5.5	V
–	Read voltage		2.7	–	5.5	V
–	Program, erase temperature		–40	–	85 (J version) 125 (K version)	°C
–	Data hold time (7)	Ambient temperature = 55 °C (8)	20	–	–	year

Notes:
1. V_{CC} = 2.7 to 5.5 V at T_{opr} = –40 to 85°C (J version) / –40 to 125°C (K version), unless otherwise specified.
2. Definition of programming/erasure endurance
   The programming and erasure endurance is defined on a per-block basis.
   If the programming and erasure endurance is n (n = 100, 1,000, 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
   However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
4. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. In addition, averaging the erasure endurance between blocks A to D can further reduce the actual erasure endurance. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
5. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
7. The data hold time includes time that the power supply is off or the clock is not supplied.
8. This data hold time includes 3,000 hours in Ta = 125°C and 7,000 hours in Ta = 85°C.

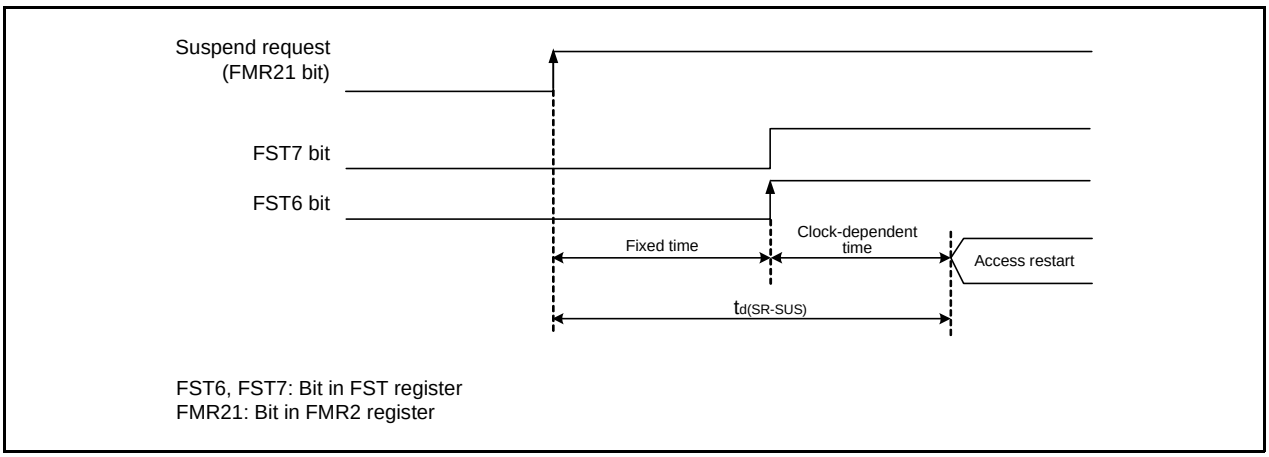
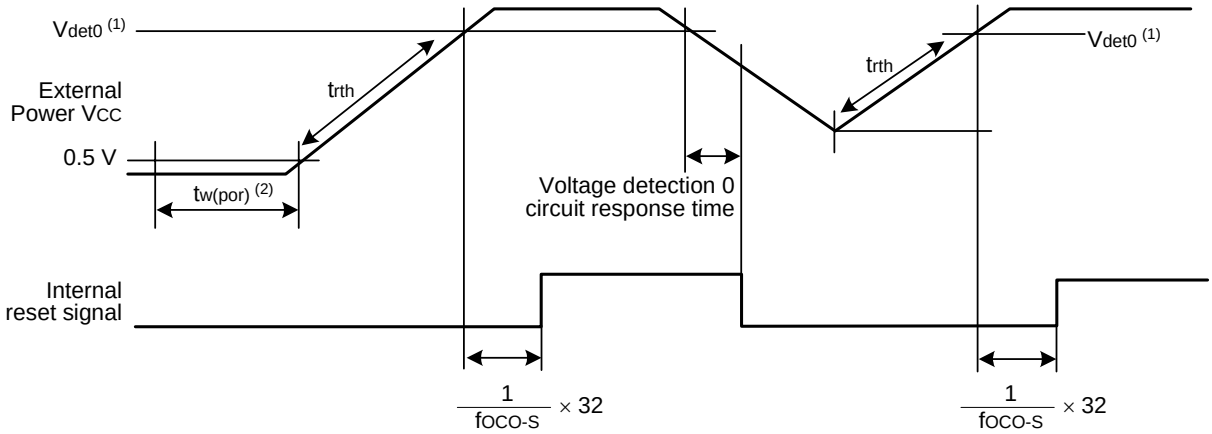


Figure 5.2 Time delay until Suspend

Table 5.10 Power-on Reset Circuit, Voltage Monitor 0 Reset Electrical Characteristics (2)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t_{rth}	External power V_{CC} rise gradient	(1)	0	–	50000	mV/msec

Notes:
1. The measurement condition is V_{CC} = 2.7 V to 5.5 V and T_{opr} = –40 to 85°C (J version) / –40 to 125°C (K version).
2. To use the power-on reset function, enable voltage monitor 0 reset by setting the LVDAS bit in the OFS register to 0.



Notes:
1. Vdet0 indicates the voltage detection level of the voltage detection 0 circuit. Refer to **6. Voltage Detection Circuit** of User's Manual: Hardware (R01UH0063EJ) for details.
2. tw(por) indicates the duration the external power VCC must be held below the valid voltage (0.5 V) to enable a power-on reset. When turning on the power after it falls with voltage monitor 0 reset disabled, maintain tw(por) for 1 ms or more.

Figure 5.3 Power-on Reset Circuit Electrical Characteristics

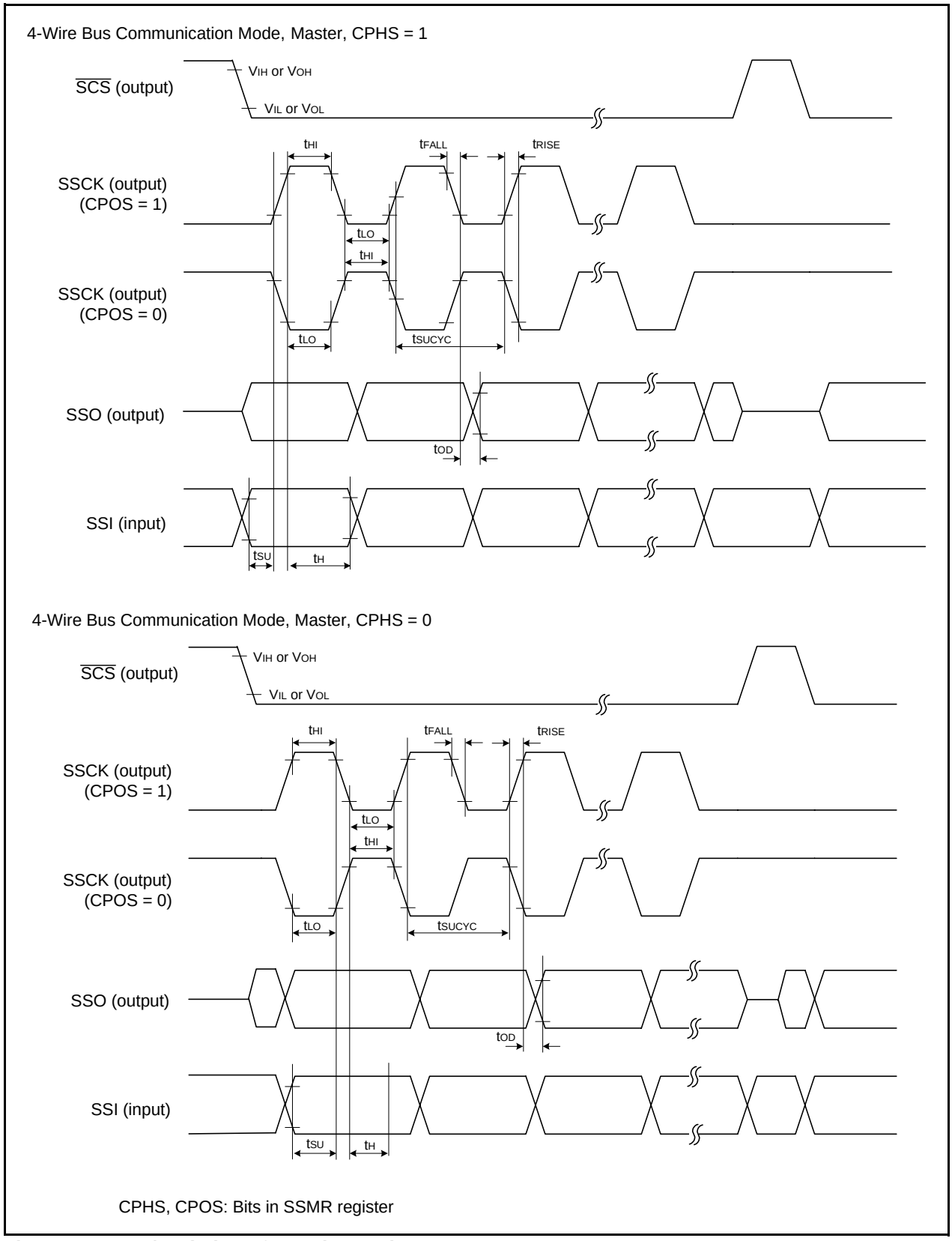


Figure 5.4 I/O Timing of SSU (Master)

Table 5.17 Electrical Characteristics (3) [3.3 V ≤ Vcc ≤ 5.5 V] (Topr = –40 to 125°C (K version), unless otherwise specified.)

Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
Icc	Power supply current (Vcc = 3.3 to 5.5 V) Single-chip mode, output pins are open, other pins are Vss	High-speed clock mode (1)	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	7.0	15	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	5.6	12.5	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	3.6	–	mA
			XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3.0	–	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2.2	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	1.5	–	mA
		High-speed on-chip oscillator mode (1)	XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	7.0	15	mA
			XIN clock off High-speed on-chip oscillator on fOCO-F = 20 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3.0	–	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR27 = 1, VCA20 = 0	–	90	400	µA
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	15	330	µA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	5	320	µA
		Stop mode	XIN clock off, Topr = 25°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	2.0	5.0	µA
			XIN clock off, Topr = 125°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	60.0	–	µA

Note:
1. The typical value (Typ.) indicates the current value when the CPU and the memory operate.
The maximum value (Max.) indicates the current when the CPU, the memory, and the peripheral functions operate and the flash memory is programmed/erased.

Timing Requirements
(Unless Otherwise Specified: Vcc = 5 V, Vss = 0 V at Topr = –40°C to 85°C (J ver)/–40°C to 125°C (K ver))

Table 5.18 External clock input (XOUT)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XOUT)}$	XOUT input cycle time	50	–	ns
$t_{WH(XOUT)}$	XOUT input “H” width	24	–	ns
$t_{WL(XOUT)}$	XOUT input “L” width	24	–	ns

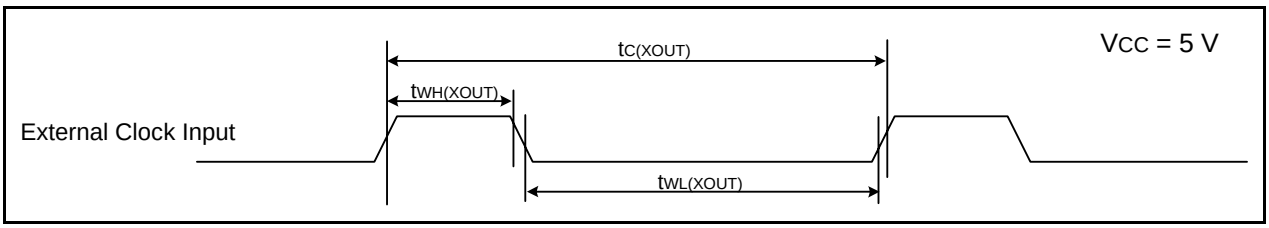


Figure 5.7 External Clock Input Timing Diagram when Vcc = 5 V

Table 5.19 TRAIO Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	100	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	40	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	40	–	ns

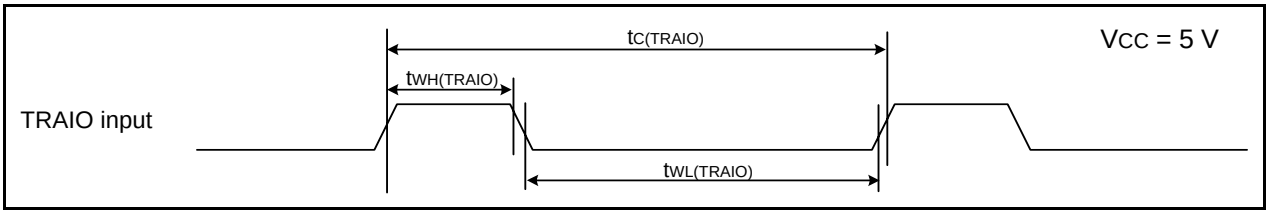


Figure 5.8 TRAIO Input Timing Diagram when Vcc = 5 V

Table 5.22 Electrical Characteristics (3) [2.7 V ≤ Vcc < 4.2 V]

Symbol	Parameter		Condition	Standard			Unit
				Min.	Typ.	Max.	
V_{OH}	Output “H” voltage	Other than XOUT	I_{OH} = –1 mA	V_{CC} – 0.5	–	V_{CC}	V
		XOUT	I_{OH} = –200 μA	1.0	–	V_{CC}	V
V_{OL}	Output “L” voltage	Other than XOUT	I_{OL} = 1 mA	–	–	0.5	V
		XOUT	I_{OL} = 200 μA	–	–	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$ to $\overline{INT4}$, $\overline{KI0}$ to $\overline{KI3}$, TRAIO, TRBO, TRCIOA to TRCIOD, TRDIOA0 to TRDIOD0, TRDIOA1 to TRDIOD1, TRCCLK, $\overline{TRDCLK}$, TRCTRG, $\overline{ADTRG}$, RXD0, RXD2, CLK0, CLK2, SSI, SCL2, SDA2, SSO		0.1	0.4	–	V
		$\overline{RESET}$		0.1	0.5	–	V
I_{IH}	Input “H” current		VI = 3 V, V_{CC} = 3.0 V	–	–	1.0	μA
I_{IL}	Input “L” current		VI = 0 V, V_{CC} = 3.0 V	–	–	–1.0	μA
R_{PULLUP}	Pull-up resistance		VI = 0 V, V_{CC} = 3.0 V	42	84	168	kΩ
R_{fXIN}	Feedback resistance	XIN		–	0.3	–	MΩ
V_{RAM}	RAM hold voltage		During stop mode	2.0	–	–	V

Note:
1. 2.7 V ≤ V_{CC} < 4.2 V at T_{opr} = –40 to 85°C (J version) / –40 to 125°C (K version), f(XIN) = 20 MHz, unless otherwise specified.

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